

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises: a semiconductor chip; an extension portion formed in contact with the side surfaces so as to surround the semiconductor chip; an insulating film formed 5 on a surface of the extension portion and the semiconductor chip; each of a plurality of wiring patterns electrically connected to each electrode pad, respectively and extended from the electrode pads to the surface of the extension portion; a sealing portion formed such that a part of each of the wiring patterns 10 is exposed; and a plurality of external terminals provided over the wiring patterns in a region including the upper side of the extension portion.